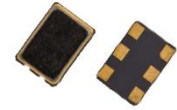


XCO382IV11-156.250



ELECTRICAL SPECIFICATIONS

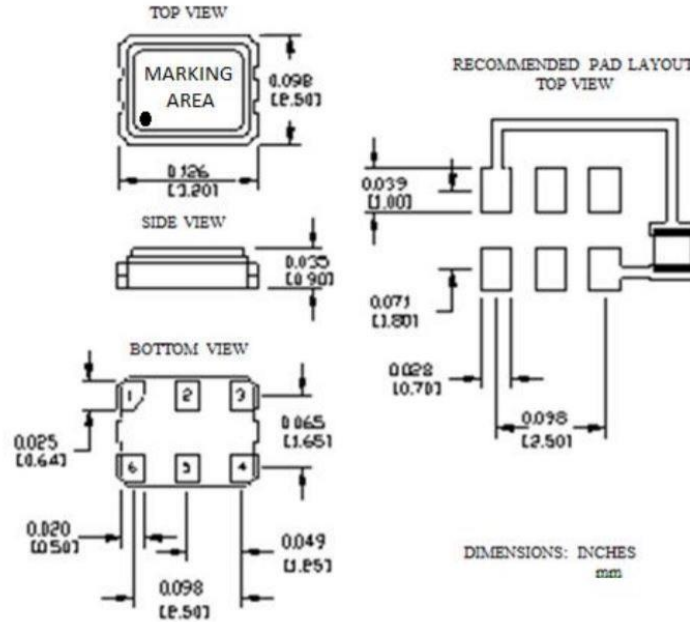
PARAMETER	SYMBOL	CONDITION	VALUE			UNIT
			Min.	Typ.	Max.	
Nominal Frequencies	F ₀			156.250		MHz
Supply Voltage	V _{cc}	25°C		2.5		V
Supply Current	I _s	2.5V ±5%			95	mA
Total Frequency Stability	st	Over -40°C to +85°C	-25		+25	ppm
Enable/Disable, PIN # 1	e/d	Enable: High Level or Open	2.25			V
		Disable: Low Level or GND			0.3	V
Start-Up Time	t _{start}	T _a =25°C			10	ms
Operating Temperature Range	T _a		-40		+85	°C
Storage Temperature Range	T _(stg)	Absolute max	-55		+125	°C
Maximum Voltage	V _{cc(abs)}	Absolute max			4.6	V
Moisture Sensitivity Level	MSL	JEDEC J-STD-2	1			
Termination Finish			3.2X2.5mm ceramic package, Nickel Silver cover, Au plating contacts.			
ESD Sensitivity	HBM	Human body model JESD22-A114			3	kV
RMS Phase Jitter	j _Σ	12 kHz – 20 MHz Bandwidth		750	950	fs

OUTPUT CHARACTERISTICS

LVDS	PARAMETER	SYMBOL	CONDITION	VALUE			UNIT
				Min	Typ.	Max	
	Differential output voltage	VOD	±5%		0.6		V
	Offset voltage	VOS	V DC		1.3		V
	Rise/fall time	Tr/Tf				0.35	ns
	Supply current	I _s				30	mA
	Output load	OCL	Differential 100Ω load connected between each output			100	Ω

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MECHANICAL DIMENSIONS AND PIN FUNCTIONING



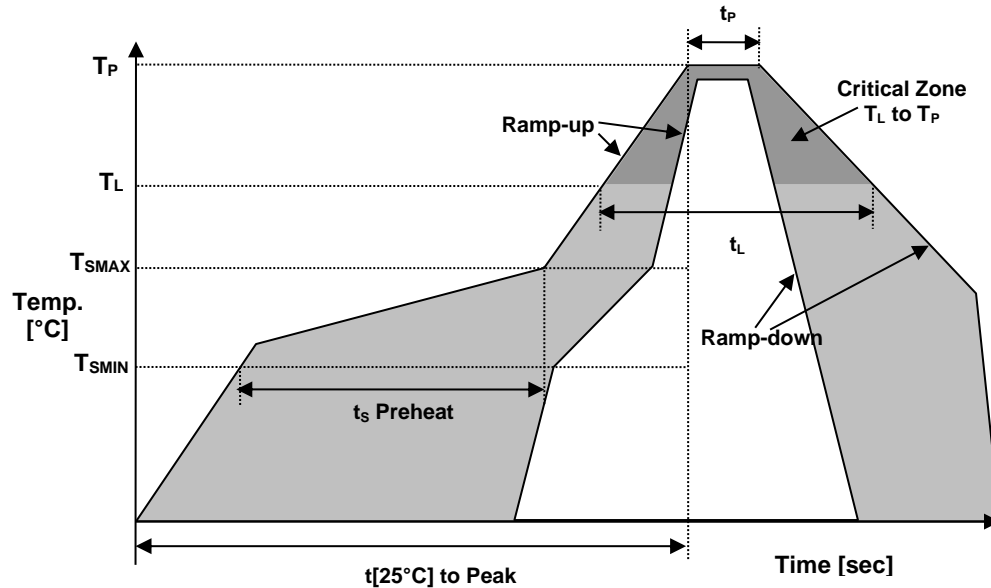
PIN	SYMBOL	FUNCTION
1	OE	Enable/Disable
2	N/C	N/C
3	GND	Case Ground
4	Q	Output
5	/Q	Complementary output
6	Vcc	Supply Voltage

■ **Marking:**

XCO
156.250
• D/C

XCO382IV11-156.250

REFLOW PROFILE



Recommended Solder Reflow Profile		
Temperature Min Preheat	T_{SMIN}	150°C
Temperature Max Preheat	T_{SMAX}	175°C
Time (T_{SMIN} to T_{SMAX})	t_s	60-180 sec.
Temperature	T_L	217°C
Peak Temperature	T_P	260°C
Ramp-up rate	R_{UP}	3°C/sec max.
Ramp-down rate	R_{DOWN}	6°C/sec max.
Time within 5°C of Peak Temperature	t_p	10 sec max.
Time $t[25^\circ\text{C}]$ to Peak Temperature	$t[25^\circ\text{C}]$ to Peak	480 sec.
Time	t_L	60-150 sec.

APPROVALS

Eng. approval, date: CP 05/19/2020

Created by, date: AR 05/19/2020

Revision: A